



Product Change Notification / LIAL-15QFEX833

Date:

08-Sep-2022

Product Category:

Microphone Preamplifiers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4733 Final Notice: Qualification of UAT as a new bumping site for AAP803A3 Microsemi catalog part number (CPN) available in 6L WLCSP (0.84x0.57x0.35mm) package.

Affected CPNs:

[LIAL-15QFEX833_Affected_CPN_09082022.pdf](#)
[LIAL-15QFEX833_Affected_CPN_09082022.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of UAT as a new bumping site for AAP803A3 Microsemi catalog part number (CPN) available in 6L WLCSP (0.84x0.57x0.35mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change

Bumping Site	Packaging Technologies (PACTECH) USA (PTUS)	Unisem Advance Tech (UAT)
Solder Ball Material	SAC 405	SAC 405
Solder Ball Pitch	300um	300um
Solder Ball Size	120um	115um
UBM Deposition Method	Electroless Ni/Au plating	Sputter + Plated
UBM Thickness	Ni/Au 5 um	0.1um Ti(sp.) + 0.2um Cu(sp.) + 8.6um Cu (pl.)

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve manufacturability by qualifying UAT as new bump site.

Change Implementation Status:In Progress

Estimated First Ship Date:September 30, 2022 (date code: 2240)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	July 2021					>	September 2022				
Workweek	2 7	2 8	2 9	3 0	3 1		3 6	3 7	3 8	3 9	4 0
Initial PCN Issue Date				X							
Qual Report Availability								X			
Final PCN Issue Date								X			
Estimated Implementation Date											X

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

July 21, 2021: Issued initial notification.

September 8, 2022: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Solder Ball Size changed to 115um. Provided estimated first ship date to be on September 30, 2022.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_LIAL-15QFEX833_Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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